

Operational Amplifier Series

Automotive Low Noise Operational Amplifiers





General Description

BA4580Yxxx-M, BA4584YFV-M integrate two or four independent Op-Amps on a single chip. These Op-Amp have some features of low noise and low distortion characteristics and can operate from ±2.0V to ±16V(split supply).

BA4560Yxxx-M, BA4584YFV-M are manufactured for automotive requirements of car navigation system, car audio, etc.

● Features

- AEC-Q100 Qualified
- High voltage gain
- low noise
- low distortion
- Wide operating supply voltage
- Internal ESD protection circuit
- Wide operating temperature Range

Application

- Car Navigation System
- Car Audio

Key Specifications

Wide operating supply voltage

(split supply):±2.0V to ±16V

Wide Temperature Range: -40°C to +105°C
 High Slew Rate: 5V/µs(Typ.)
 Total Harmonic Distortion: 0.0005%(Typ.)
 Input Referred Noise Voltage: 5 nV/√Hz (Typ.)

 ●Packages
 W(Typ.) xD(Typ.) xH(Max.)

 SOP8
 5.00mm x 6.20mm x 1.71mm

 MSOP8
 2.90mm x 4.00mm x 0.90mm

 SSOP-B14
 5.00mm x 6.40mm x 1.35mm

Simplified schematic

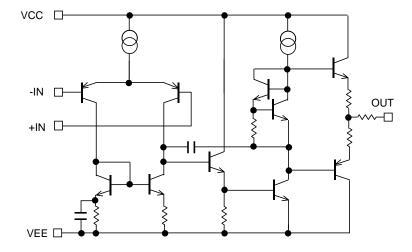
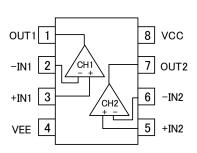


Figure 1. Simplified schematic (one channel only)

OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

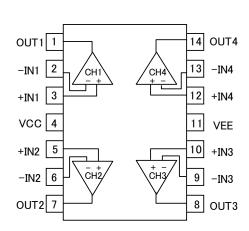
●Pin Configuration

BA4580YF-M: SOP8 BA4580YFVM-M: MSOP8



Pin No.	Symbol
1	OUT1
2	-IN1
3	+IN1
4	VEE
5	+IN2
6	-IN2
7	OUT2
8	VCC

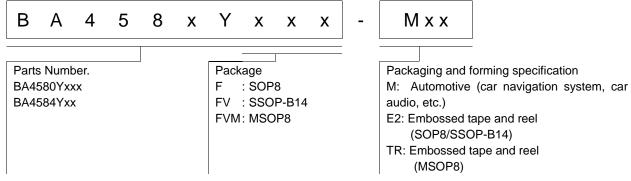
BA4584YFV-M: SSOP-B14



Pin No.	Symbol
1	OUT1
2	-IN1
3	+IN1
4	VCC
5	+IN2
6	-IN2
7	OUT2
8	OUT3
9	-IN3
10	+IN3
11	VEE
12	+IN4
13	-IN4
14	OUT4

Package							
SOP8	MSOP8	SSOP-B14					
BA4580YF-M	BA4580YFVM-M	BA4584YFV-M					

Ordering Information



●Line-up

Topr	Supply voltage	Number of channels	Package		Orderable Parts Number
		Dual	SOP8	Reel of 2500	BA4580YF-ME2
-40°C to +105°C	±2.0V to ±16V	Dual	MSOP8	Reel of 3000	BA4580YFVM-MTR
		Quad	SSOP-B14	Reel of 2500	BA4584YFV-ME2

● Absolute Maximum Ratings (Ta=25°C)

Davamatav	Cymhal		Rati	Unit	
Parameter		Symbol	BA4580Y	BA4580Y BA4584Y	
Supply Voltage	VCC-VEE		+3	36	V
		SOP8	780 ^{*1*4}	-	
Power Dissipation	Pd	MSOP8	590 ^{*2*4}	-	mW
		SSOP-B14	-	1350 ^{*3*4}	
Differential Input Voltage *5	Vid		+3	V	
Input Common-mode Voltage Range		Vicm	(VEE-0.3) to	V	
Input Current *6		li	-10		mA
Operating Supply Voltage		Vonr		+32 ±16)	V
Output current		lout	±5	50	mA
Operating Temperature Range	Topr		-40 to +105		°C
Storage Temperature Range	Tstg		-55 to +150		°C
Maximum Junction Temperature		Tjmax	+1	50	°C

Note: Absolute maximum rating item indicates the condition which must not be exceeded. Application if voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

To use at temperature above Ta=25°C reduce 6.2mW/°C.

To use at temperature above Ta=25°C reduce 4.8mW/°C.
To use at temperature above Ta=25°C reduce 4.8mW/°C.
To use at temperature above Ta=25°C reduce 10.8mW/°C.
Mounted on a FR4 glass epoxy PCB(70mm×70mm×1.6mm).

The voltage difference between inverting input and non-inverting input is the differential input voltage. Then input terminal voltage is set to more than VEE.

Excessive input current will flow if a differential input voltage in excess of approximately 0.6V is applied between the input unless some limiting resistance is used.

Electrical Characteristics

OBA4580Yxxx-M (Unless otherwise specified VCC=+15V, VEE=-15V, Ta=25°C)

D	Oh al		Limits	<u>, , , , , , , , , , , , , , , , , , , </u>		O and ditions	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
Input Offset Voltage *7	Vio	-	0.3	3	mV	RS≦10kΩ	
Input Offset Current *7	lio	-	5	200	nA	-	
Input Bias Current *8	lb	-	100	500	nA	-	
Supply Current	ICC	-	6	9	mA	RL=∞, All Op-Amps, VIN+=0V	
Maximum Output Voltage	VOM	±12	±13.5	-	V	RL≧2kΩ	
Large Signal Voltage Gain	Av	90	110	-	dB	RL≧10kΩ, OUT=±10 V	
Input Common-mode Voltage Range	Vicm	±12	±13.5	-	V	-	
Common-mode Rejection Ratio	CMRR	80	110	-	dB	RS≦10kΩ	
Power Supply Rejection Ratio	PSRR	80	110	-	dB	RS≦10kΩ	
Slew Rate	SR	-	5	-	V/µs	RL≧2kΩ	
Gain Band Width	GBW	-	10	-	MHz	f=10kHz	
Unity Gain Frequency	f⊤	-	5	-	MHz	RL=2kΩ	
Total Harmonic Distortion +Noise	THD+N	ı	0.0005	-	%	Av=20dB, OUT=5Vrms RL=2kΩ f=1kHz, 20Hz~20kHz BPF	
Input Referred Noise Voltage	Vn	ı	5	-	nV/√Hz	RS=100Ω, Vi=0V, f=1kHz	
The reletted Noise vollage	VII	1	0.8	-	μVrms	RIAA, RS=2.2 kΩ, 30kHz LPF	
Channel Separation	CS	-	110	-	dB	R1=100Ω, f=1kHz	

⁷ Absolute value

^{*8} Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

OBA4584Y (Unless otherwise specified VCC=+15V, VEE=-15V, Ta=25°C)

Parameter	Symbol		Limits		Unit	Condition	
i alametei	Symbol	Min.	Тур.	Max.	Offic	Condition	
Input Offset Voltage *9	Vio	-	0.3	3	mV	RS≦10kΩ	
Input Offset Current *9	lio	-	5	200	nA	-	
Input Bias Current *10	lb	-	100	500	nA	-	
Supply Current	ICC	-	11	17	mA	RL=∞, All Op-Amps, VIN+=0V	
Maximum Output Voltage	VOM	±12	±13.5	-	V	RL≧2kΩ	
Large Signal Voltage Gain	AV	90	110	-	dB	RL≧10kΩ, OUT=±10V	
Input Common-mode Voltage Range	Vicm	±12	±13.5	-	V	-	
Common-mode Rejection Ratio	CMRR	80	110	-	dB	RS≦10kΩ	
Power Supply Rejection Ratio	PSRR	80	110	-	dB	RS≦10kΩ	
Slew Rate	SR	-	5	-	V/µs	RL≧2kΩ	
Gain Band Width	GBW	-	10	-	MHz	f=10kHz	
Unity Gain Frequency	f⊤	-	5	-	MHz	RL=2kΩ	
Total Harmonic Distortion +Noise	THD+N	-	0.0005	-	%	Av=20dB, OUT=5Vrms RL=2kΩ f=1kHz, 20Hz~20kHz BPF	
Input Referred Noise Voltage	Vn	-	5	-	nV/√Hz	RS=100Ω, Vi=0V, f=1kHz	
input ivereneu ivoise voitage	VII	-	0.8	-	μVrms	RIAA, RS=2.2kΩ, 30kHz LPF	
Channel Separation	CS	-	110	-	dB	R1=100Ω, f=1kHz	

^{*9} Absolute value

^{*10} Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

Description of electrical characteristics

Described here are the terms of electric characteristics used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacture's document or general document.

1. Absolute maximum ratings

Absolute maximum rating item indicates the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

1.1 Power supply voltage (VCC-VEE)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

1.2 Differential input voltage (Vid)

Indicates the maximum voltage that can be applied between non-inverting terminal and inverting terminal without deterioration and destruction of characteristics of IC.

1.3 Input common-mode voltage range (Vicm)

Indicates the maximum voltage that can be applied to non-inverting terminal and inverting terminal without deterioration or destruction of characteristics. Input common-mode voltage range of the maximum ratings not assure normal operation of IC. When normal operation of IC is desired, the input common-mode voltage of characteristics item must be followed.

1.4 Power dissipation (Pd)

Indicates the power that can be consumed by specified mounted board at the ambient temperature 25°C(normal temperature). As for package product, Pd is determined by the temperature that can be permitted by IC chip in the package (maximum junction temperature) and thermal resistance of the package.

2. Electrical characteristics item

2.1 Input offset voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminal. It can be translated into the input voltage difference required for setting the output voltage at 0V.

2.2 Input offset current (lio)

Indicates the difference of input bias current between non-inverting terminal and inverting terminal.

2.3 Input bias current (Ib)

Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias current at non-inverting terminal and input bias current at inverting terminal.

2.4 Circuit current (ICC)

Indicates the IC current that flows under specified conditions and no-load steady status.

2.5 Output saturation voltage (VOM)

Signifies the voltage range that can be output under specific output conditions.

2.6 Large signal voltage gain (Av)

Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and Inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.

Av = (Output voltage) / (Differential Input voltage)

2.7 Input common-mode voltage range (Vicm)

Indicates the input voltage range where IC operates normally.

2.8 Common-mode rejection ratio (CMRR)

Indicates the ratio of fluctuation of input offset voltage when in-phase input voltage is changed. It is normally the fluctuation of DC.

CMRR = (Change of Input common-mode voltage)/(Input offset fluctuation)

2.9 Power supply rejection ratio (PSRR)

Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC.

PSRR = (Change of power supply voltage) / (Input offset fluctuation)

2.10 Slew Rate (SR)

SR is a parameter that shows movement speed of operational amplifier. It indicates rate of variable output voltage as unit time.

2.11 Gain Band Width (GBW)

The product of the open-loop voltage gain and the frequency at which the voltage gain decreases 6dB/octave.

2.12 Unity gain frequency (f_T)

Indicates a frequency where the voltage gain of operational amplifier is 1.

2.13 Total harmonic distortion + Noise (THD+N)

Indicates the fluctuation of input offset voltage or that of output voltage with reference to the change of output voltage of driven channel.

2.14 Input referred noise voltage (Vn)

Indicates a noise voltage generated inside the operational amplifier equivalent by ideal voltage source connected in series with input terminal.

2.15 Channel separation (CS)

Indicates the fluctuation of input offset voltage or that of output voltage with reference to the change of output voltage of driven channel.

●Typical Performance Curves

O BA4580Yxxx-M

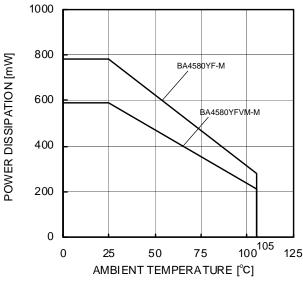


Figure 2.
Derating Curve

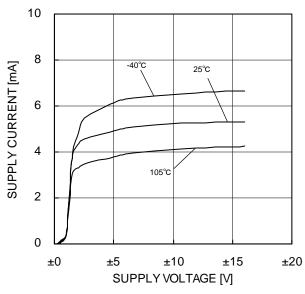


Figure 3.
Supply Current - Supply Voltage

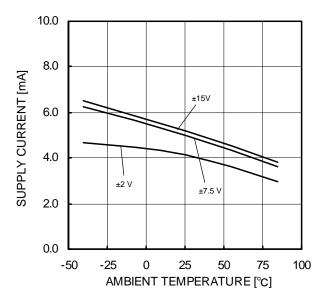


Figure 4.
Supply Current - Ambient Temperature

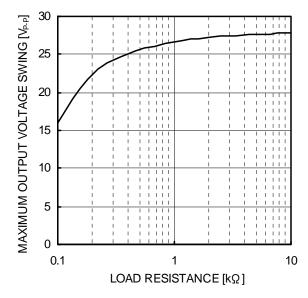


Figure 5.

Maximum Output Voltage Swing
- Load Resistance
(VCC/VEE=+15V/-15V,Ta=25°C)

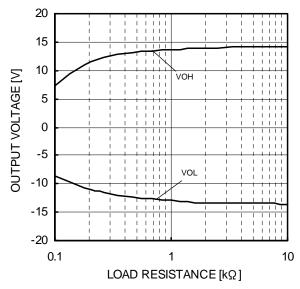


Figure 6.

Maximum Output Voltage

- Load Resistance
(VCC/VEE=+15V/-15V,Ta=25°C)

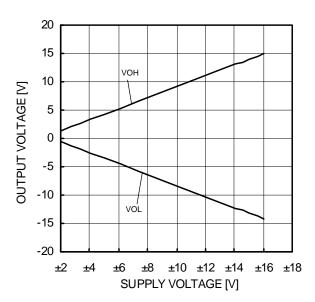


Figure 7.

Maximum Output Voltage
- Supply Voltage
(RL=2kΩ,Ta=25°C)

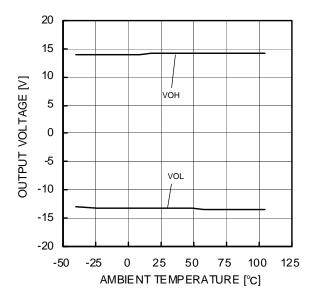


Figure 8.

Maximum Output Voltage
- Ambient Temperature
(VCC/VEE=+15V/-15V, RL=2kΩ)

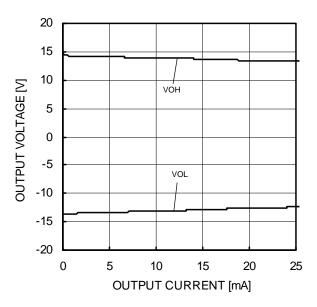


Figure 9.

Maximum Output Voltage
- Output Current
(VCC/VEE=+15V/-15V, Ta=25°C)

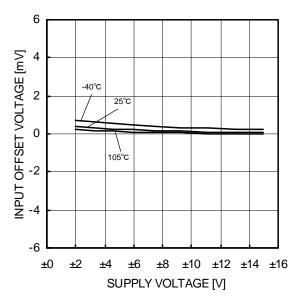


Figure 10.
Input Offset Voltage - Supply Voltage
(Vicm=0V, OUT=0V)

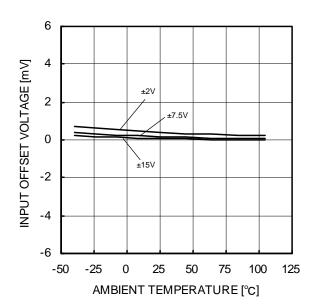


Figure 11.
Input Offset Voltage - Ambient Temperature
(Vicm=0V, OUT=0V)

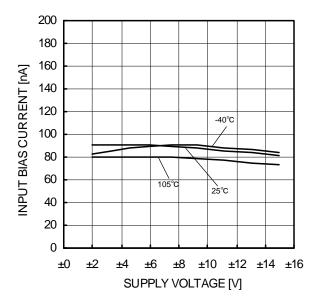


Figure 12.
Input Bias Current - Supply Voltage
(Vicm=0V, OUT=0V)

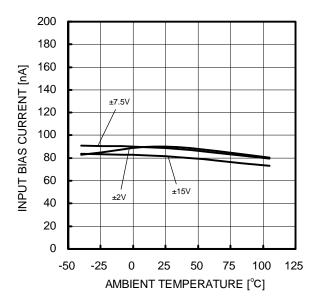


Figure 13.
Input Bias Current - Ambient Temperature
(Vicm=0V, OUT=0V)

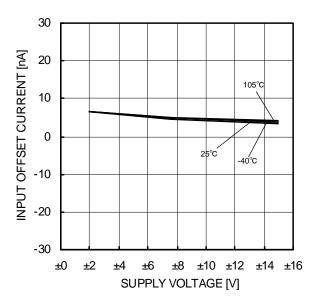


Figure 14.
Input Offset Current - Supply Voltage
(Vicm=0V, OUT=0V)

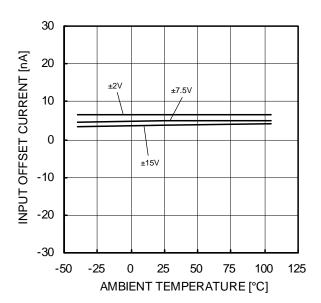


Figure 15.
Input Offset Current - Ambient Temperature
(Vicm=0V, OUT=0V)

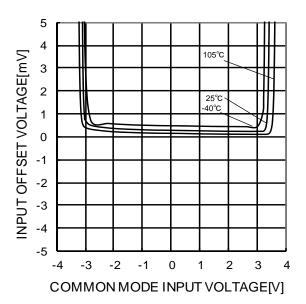


Figure 16.
Input Offset Voltage
- Common Mode Input Voltage
(VCC/VEE=+4V/-4V, OUT=0V)

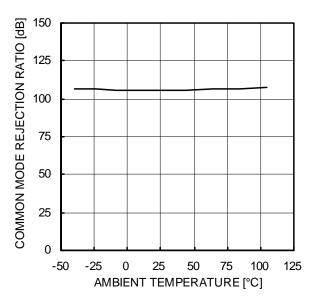


Figure 17.
Common Mode Rejection Ratio
- Ambient Temperature
(VCC/VEE=+15V/-15V, Vicm=-12V ~ +12V)

(*) The above data is measurement value of typical sample, it is not guaranteed.

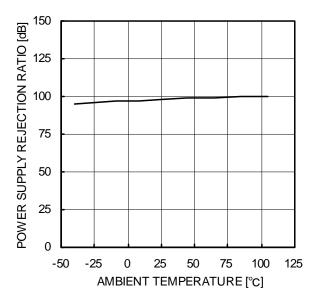


Figure 18.
Power Supply Rejection Ratio
- Ambient Temperature
(VCC/VEE=+2V/-2V ~ +15V/-15V)

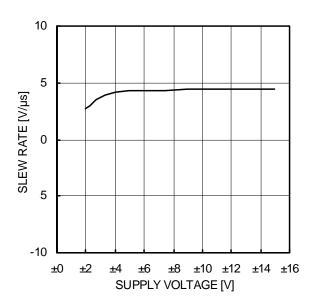


Figure 19. Slew Rate - Supply Voltage (CL=100pF, RL=2k Ω , Ta=25 $^{\circ}$ C)

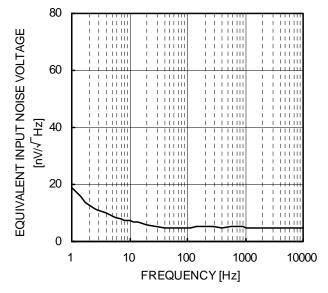


Figure 20. Equivalent Input Noise Voltage - Frequency (VCC/VEE=+15V/-15V, RS=100 Ω , Ta=25 $^{\circ}$ C)

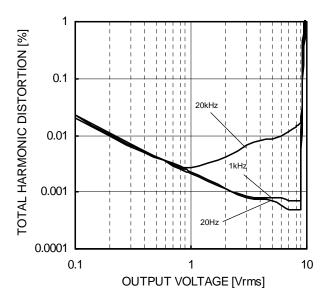


Figure 21. Total Harmonic Distortion - Output Voltage (VCC/VEE=+15V/-15V, Av=20dB, RL= $2k\Omega$, 80kHz-LPF, $Ta=25^{\circ}C$)

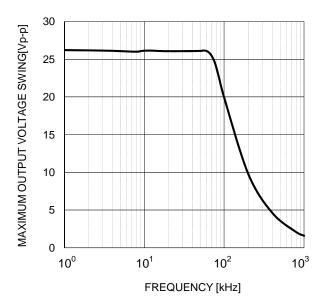


Figure 22.

Maximum Output Voltage Swing – Frequency (VCC/VEE=+15V/-15V, RL=2kΩ, Ta=25°C)

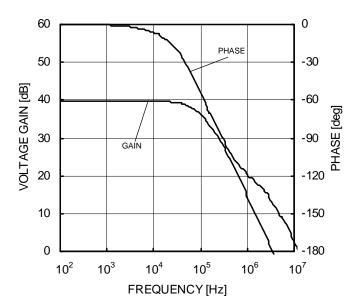
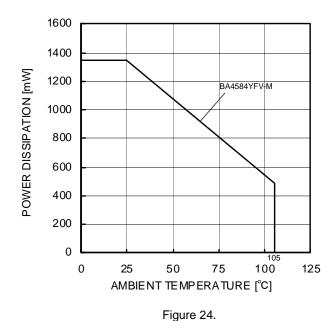


Figure 23.
Voltage Gain, Phase - Frequency
(VCC/VEE=+15V/-15V, Av=40dB, RL=2kΩ, Ta=25°C)



Derating Curve

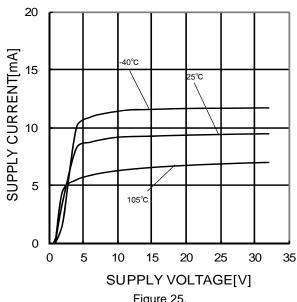


Figure 25. Supply Current - Supply Voltage

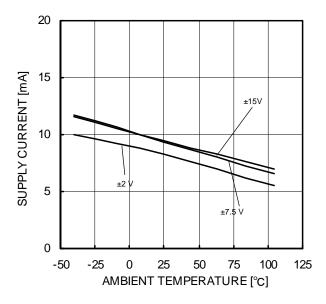


Figure 26.
Supply Current - Ambient Temperature

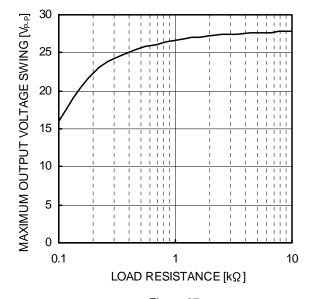


Figure 27.

Maximum Output Voltage Swing
- Load Resistance
(VCC/VEE=+15V/-15V, Ta=25°C)

(*) The above data is measurement value of typical sample, it is not guaranteed.

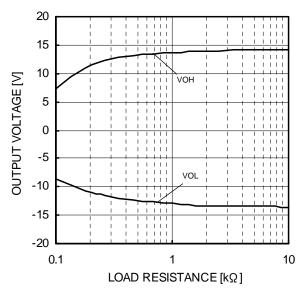


Figure 28.

Maximum Output Voltage
- Load Resistance
(VCC/VEE=+15V/-15V, Ta=25°C)

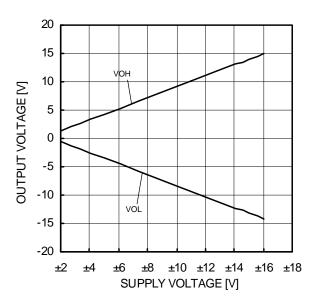


Figure 29.

Maximum Output Voltage
- Supply Voltage
(RL=2kΩ, Ta=25°C)

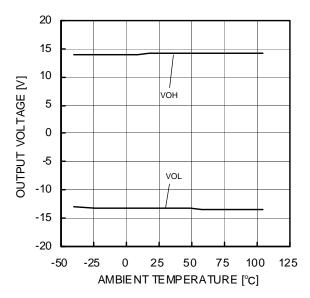


Figure 30.

Maximum Output Voltage
- Ambient Temperature
(VCC/VEE=+15V/-15V, RL=2kΩ)

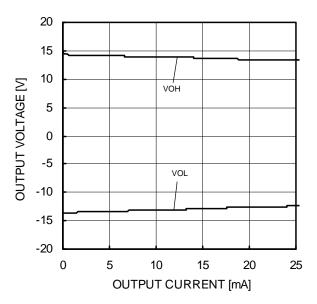


Figure 31.

Maximum Output Voltage
- Output Current
(VCC/VEE=+15V/-15V, Ta=25°C)

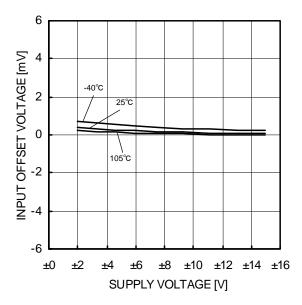


Figure 32.
Input Offset Voltage - Supply Voltage
(Vicm=0V, OUT=0V)

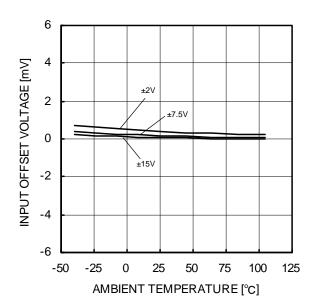


Figure 33.
Input Offset Voltage - Ambient Temperature
(Vicm=0V, OUT=0V)

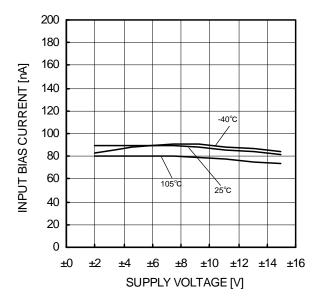


Figure 34.
Input Bias Current - Supply Voltage (Vicm=0V, OUT=0V)

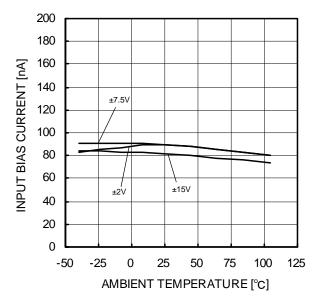


Figure 35.
Input Bias Current - Ambient Temperature
(Vicm=0V, OUT=0V)

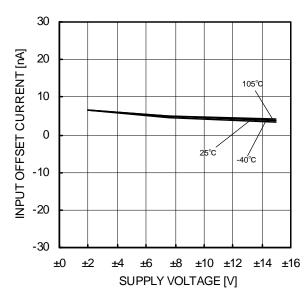


Figure 36.
Input Offset Current - Supply Voltage
(Vicm=0V, OUT=0V)

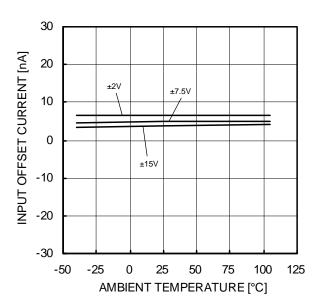


Figure 37.
Input Offset Current - Ambient Temperature
(Vicm=0V, OUT=0V)

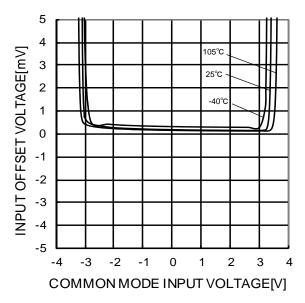


Figure 38.
Input Offset Voltage
- Common Mode Input Voltage
(VCC/VEE=+4V/-4V, OUT=0V)

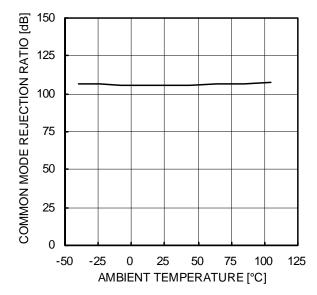


Figure 39.
Common Mode Rejection Ratio
- Ambient Temperature
(VCC/VEE=+15V/-15V, Vicm=-12V ~ +12V)

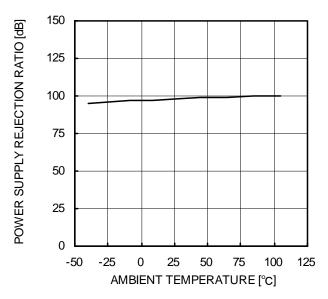


Figure 40.
Power Supply Rejection Ratio
- Ambient Temperature
(VCC/VEE=+2V/-2V ~ +15V/-15V)

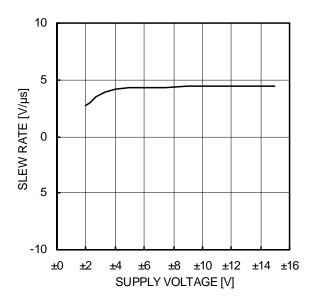


Figure 41. Slew Rate - Supply Voltage (CL=100pF, RL=2k Ω , Ta=25 $^{\circ}$ C)

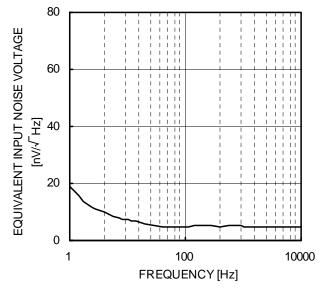


Figure 42.
Equivalent Input Noise Voltage - Frequency (VCC/VEE=+15V/-15V, RS=100Ω, Ta=25°C)

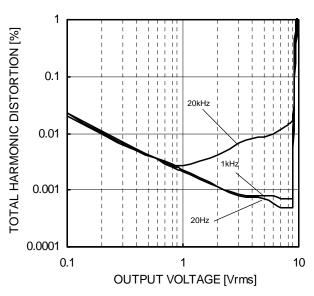


Figure 43.

Total Harmonic Distortion - Output Voltage (VCC/VEE=+15V/-15V, Av=20dB, RL=2kΩ, 80kHz-LPF, Ta=25°C)

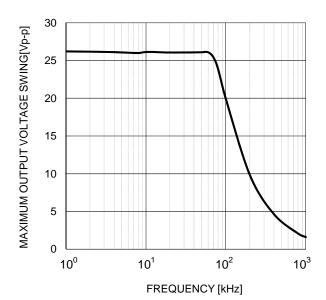
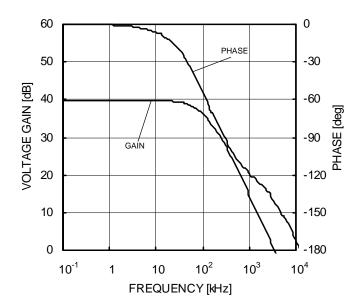


Figure 44.

Maximum Output Voltage Swing – Frequency (VCC/VEE=+15V/-15V, RL=2kΩ, Ta=25°C)



 $\label{eq:Figure 45.} Figure 45. \\ Voltage Gain, Phase - Frequency \\ (VCC/VEE=+15V/-15V, Av=40dB, RL=2k\Omega, Ta=25^{\circ}C)$

Power Dissipation

Power dissipation (total loss) indicates the power that the IC can consume at Ta=25°C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol θ ja°C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 46. (a) shows the model of the thermal resistance of the package. The equation below shows how to compute for the Thermal resistance (θ)a), given the ambient temperature (Ta), maximum junction temperature (Tjmax), and power dissipation (Pd).

$$\theta$$
ja = (Tjmax - Ta) / Pd °C/W · · · · · (I)

The Derating curve in Figure 46. (b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance (θja), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 47. (c),(d) shows an example of the derating curve for BA4580Yxxx-M, BA4584YFV-M.

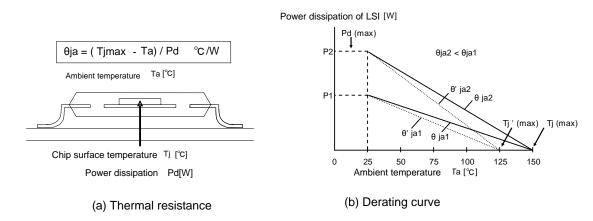
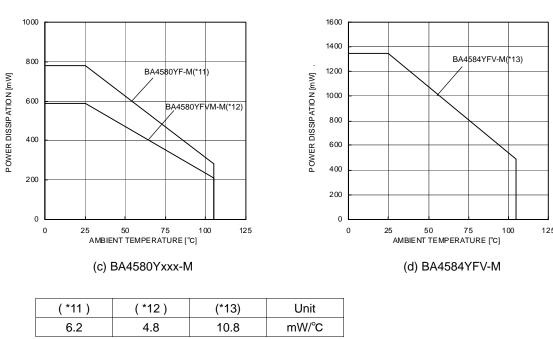


Figure 46. Thermal resistance and derating



When using the unit above Ta=25°C, subtract the value above per Celsius degree . Mounted on a FR4 glass epoxy board 70mm×70mm×1.6mm(cooper foil area below 3%)

Figure 47. Derating curve

Application Information

NULL method condition for Test circuit1

	111.1								VCC,	VEE, E	K Unit: V
Developed	\/_	04	60	00 00	BA4580Y			BA4584Y			
Parameter	VF	S1	S2	S3	VCC	VEE	EK	VCC	VEE	EK	calculation
Input Offset Voltage	VF1	ON	ON	OFF	15	-15	0	15	-15	0	1
Input Offset Current	VF2	OFF	OFF	OFF	15	-15	0	15	-15	0	2
	VF3	OFF	ON OFF	OFF	15	15 15	15 0	15	-15	0	3
Input Bias Current	VF4	ON				-15					3
Laura Simal Valtara Caia	VF5	011	ON	ON	15	-15	-10	15	-15	-10	4
Large Signal Voltage Gain	VF6	ON	ON	ON	15	-15	10	15	-15	10	4
Common-mode Rejection Ratio	VF7	ON	ON	OFF	3	-27	12	3	-27	12	-
(Input common-mode Voltage Range)	VF8	ON	ON	OFF	27	-3	-12	27	-3	-12	5
Power Supply	VF9	ON	ON	OFF	4	-2	0	2	-2	0	6
Rejection Ratio	VF10	ON	ON ON	OFF	15	-15	0	15	-15	0	6

- Calculation -
- 1. Input Offset Voltage (Vio)

$$Vio = \frac{\mid VF1 \mid}{1 + RF/RS} \quad [V]$$

2. Input Offset Current (lio)

$$Iio = \frac{|VF2-VF1|}{Ri \times (1+RF/RS)} \quad [A]$$

3. Input Bias Current (lb)

$$Ib = \frac{\left| VF4 - VF3 \right|}{2 \times Ri \times (1 + RF/RS)} \quad [A]$$

4. Large Signal Voltage Gain (Av)

$$Av = 20 \times Log \frac{\Delta EK \times (1+RF/RS)}{\mid VF5 - VF6 \mid} \quad [dB]$$

5. Common-mode Rejection Ration (CMRR)

$$CMRR = 20 \times Log \frac{\Delta Vicm \times (1 + RF/RS)}{ \mid VF8 - VF7 \mid} \quad [dB]$$

6. Power supply rejection ratio (PSRR)

$$PSRR = 20 \times Log \frac{\Delta Vcc \times (1 + RF/RS)}{\left| VF10 - VF9 \right|} \quad [dB]$$

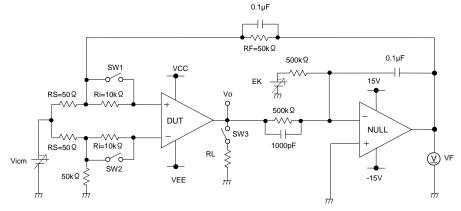


Figure 48. Test circuit1 (one channel only)

Switch Condition for Test Circuit 2

SW No.	SW1	SW2	SW3	SW4	SW5	SW6	SW7	SW8	SW9	SW10	SW11	SW12	SW13	SW14
Supply Current	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage (high)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Maximum Output Voltage (Low)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF
Output Source Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Output Sink Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Slew Rate	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	OFF
Gain Band Width	OFF	ON	OFF	OFF	ON	ON	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Input Referred Noise Voltage	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF

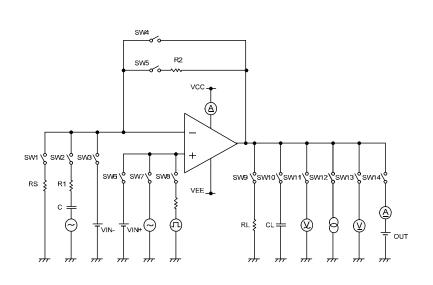


Figure 49. Test Circuit 2 (each Op-Amp)

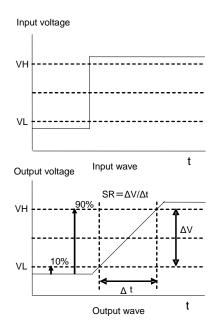


Figure 50. Slew Rate Input Waveform

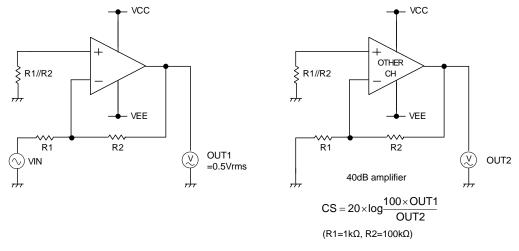


Figure 51. Test Circuit 3(Channel Separation)

Examples of circuit

OVoltage follower

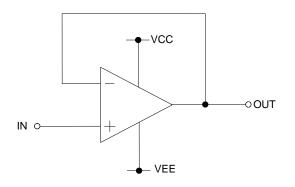


Figure 52. Voltage follower circuit

Voltage gain is 0dB.

Using this circuit, the output voltage (OUT) is configured to be equal to the input voltage (IN). This circuit also stabilizes the output voltage (OUT) due to high input impedance and low output impedance. Computation for output voltage (OUT) is shown below. OUT=IN

OInverting amplifier

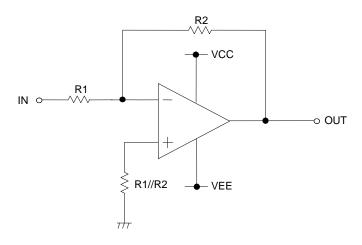


Figure 53. Inverting amplifier circuit

For inverting amplifier, input voltage (IN) is amplified by a voltage gain and depends on the ratio of R1 and R2. The out-of-phase output voltage is shown in the next expression

OUT=-(R2/R1) · IN

This circuit has input impedance equal to R1.

ONon-inverting amplifier

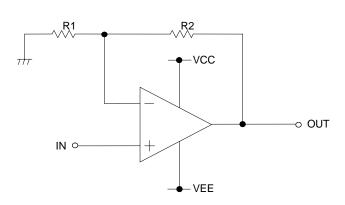


Figure 54. Non-inverting amplifier circuit

For non-inverting amplifier, input voltage (IN) is amplified by a voltage gain, which depends on the ratio of R1 and R2. The output voltage (OUT) is in-phase with the input voltage (IN) and is shown in the next expression.

OUT=(1 + R2/R1) · IN

Effectively, this circuit has high input impedance since its input side is the same as that of the operational amplifier.

Operational Notes

1) Processing of unused circuit

It is recommended to apply connection (see the Figure 55.) and set the non inverting input terminal at the potential within input common-mode voltage range (Vicm), for any unused circuit.

2) Input voltage

Applying (VEE - 0.3) to (VEE + 36)V

(BA4558R) to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, irrespective of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

3) Maximum output voltage

Because the output voltage range becomes narrow as the output current Increases, design the application with margin by considering changes in electrical characteristics and temperature characteristics.

4) Short-circuit of output terminal

When output terminal and VCC or VEE terminal are shorted, excessive Output current may flow under some conditions, and heating may destroy IC. It is necessary to connect a resistor as shown in Figure 56., thereby protecting against load shorting.

5) Power supply (split supply / single supply) in used

Op-amp operates when specified voltage is applied between VCC and VEE. Therefore, the single supply Op-Amp can be used for double supply Op-Amp as well.

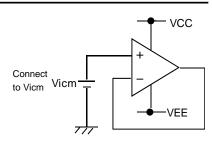


Figure 55. The example of application circuit for unused op-amp

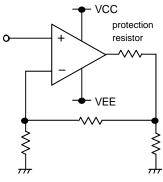


Figure 56. The example of output short protection

6) Power dissipation (Pd)

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

7) Short-circuit between pins and wrong mounting

Pay attention to the assembly direction of the ICs. Wrong mounting direction or shorts between terminals, GND, or other components on the circuits, can damage the IC.

8) Use in strong electromagnetic field

Using the ICs in strong electromagnetic field can cause operation malfunction.

9) Radiation

This IC is not designed to be radiation-resistant.

10) IC Handling

When stress is applied to IC because of deflection or bend of board, the characteristics may fluctuate due to piezo resistance effects.

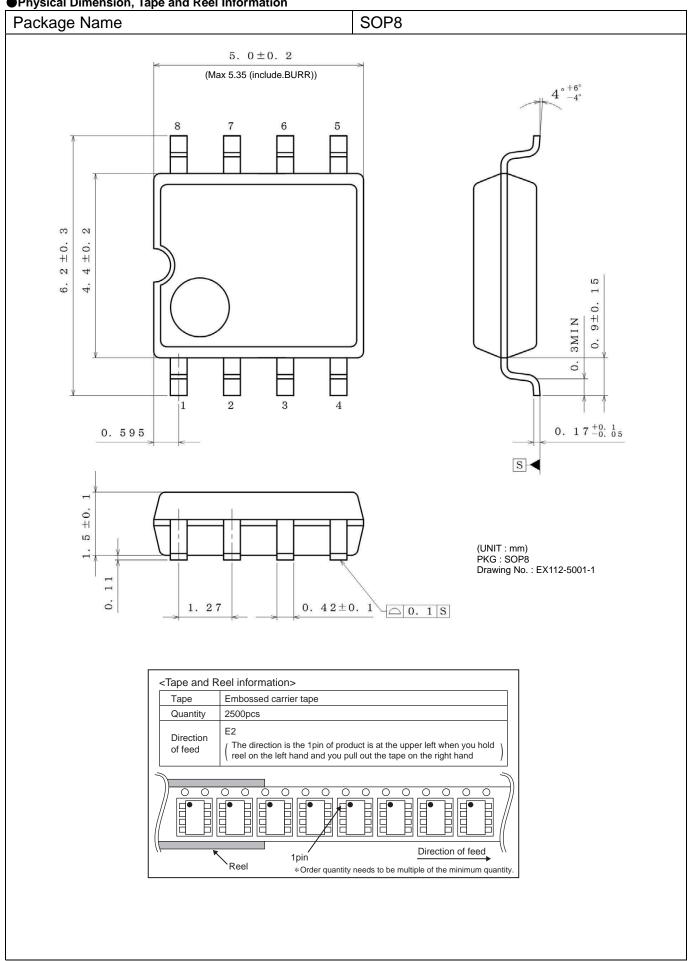
11) Inspection on set board

During testing, turn on or off the power before mounting or dismounting the board from the test Jig. Do not power up the board without waiting for the output capacitors to discharge. The capacitors in the low output impedance terminal can stress the device. Pay attention to the electro static voltages during IC handling, transportation, and storage.

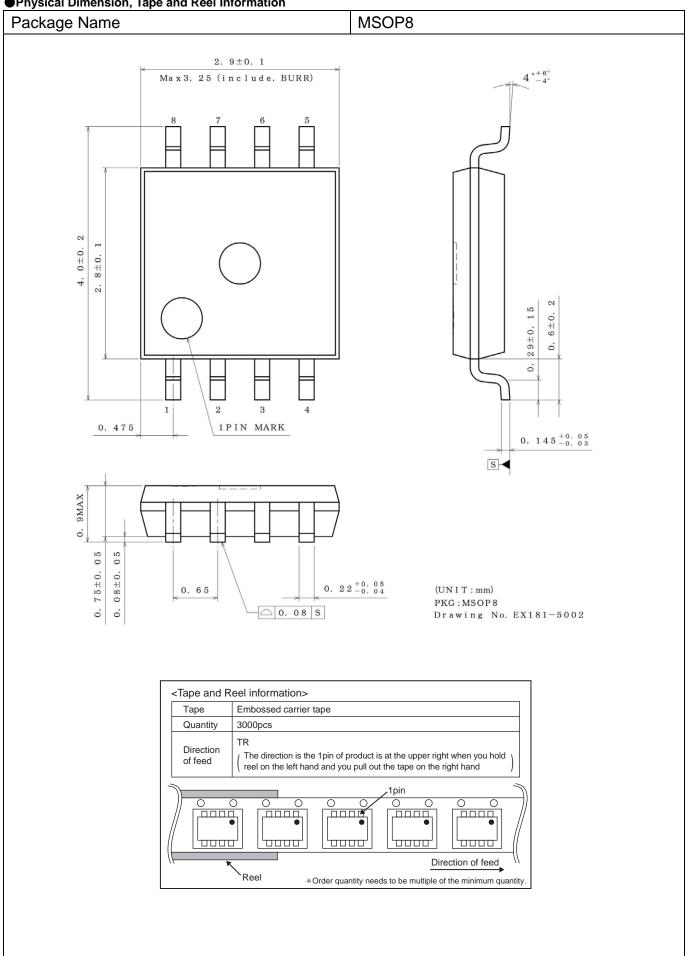
12) Output capacitor

When VCC terminal is shorted to VEE (GND) potential and an electric charge has accumulated on the external capacitor, connected to output terminal, accumulated charge may be discharged VCC terminal via the parasitic element within the circuit or terminal protection element. The element in the circuit may be damaged (thermal destruction). When using this IC for an application circuit where there is oscillation, output capacitor load does not occur, as when using this IC as a voltage comparator. Set the capacitor connected to output terminal below 0.1µF in order to prevent damage to IC.

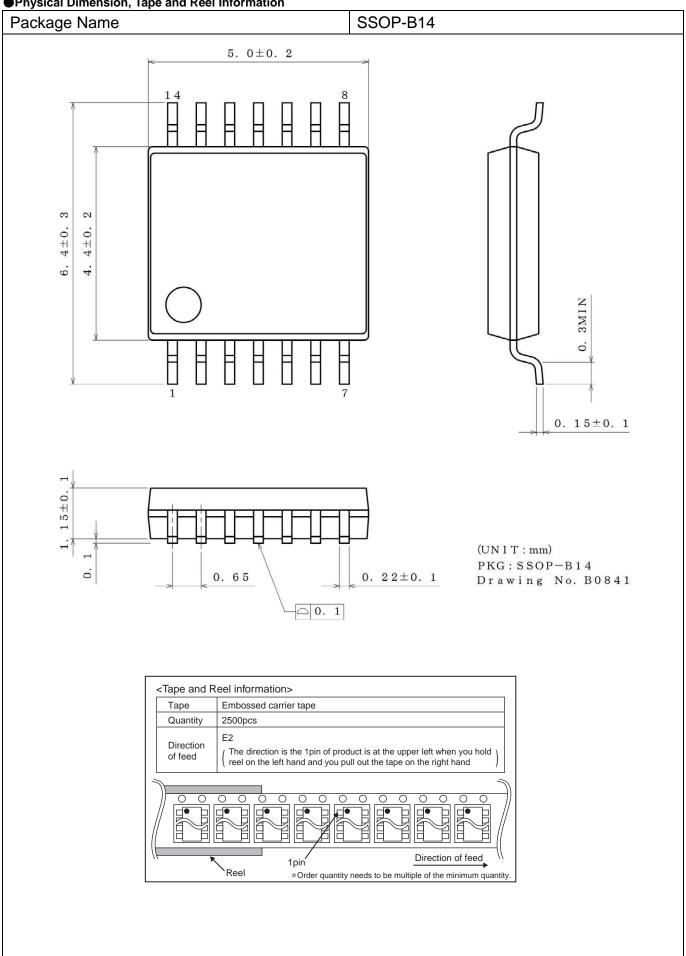
●Physical Dimension, Tape and Reel Information



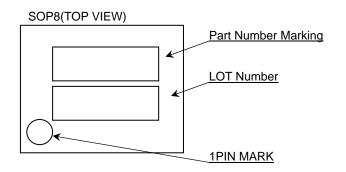
●Physical Dimension, Tape and Reel Information

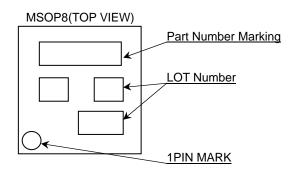


●Physical Dimension, Tape and Reel Information

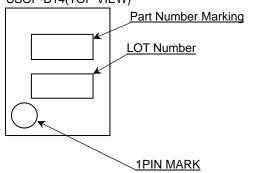


Marking Diagram





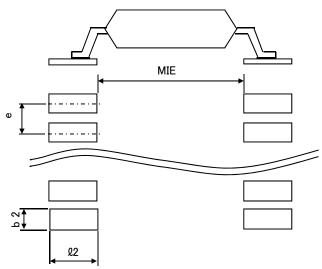
SSOP-B14(TOP VIEW)



Product N	ame	Package Type	Marking
BA4580Y	F-M	SOP8	80YM
DA43601	FVM-M	MSOP8	80YM
BA4584Y	FV-M	SSOP-B14	4584Y

Land pattern data

SOP8, SSOP-B8, MSOP8



All dimensions in mm

PKG	Land pitch e	Land space MIE	Land length ≧ℓ 2	Land width b2
SOP8	1.27	4.60	1.10	0.76
MSOP8	0.65	2.62	0.99	0.35
SSOP-B14	0.65	4.60	1.20	0.35

Revision History

Date	Revision	Changes
2012. 7. 6	001	New Release
2013. 3. 25	002	Added BA4580Y

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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